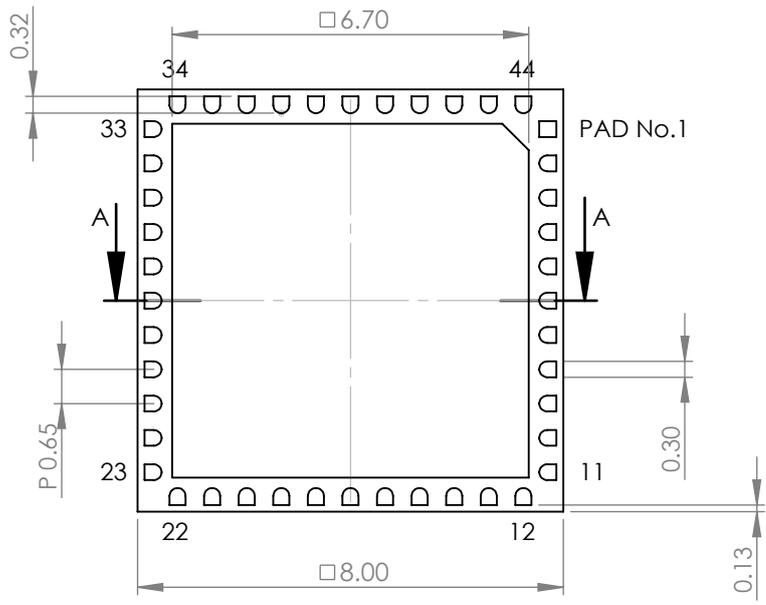


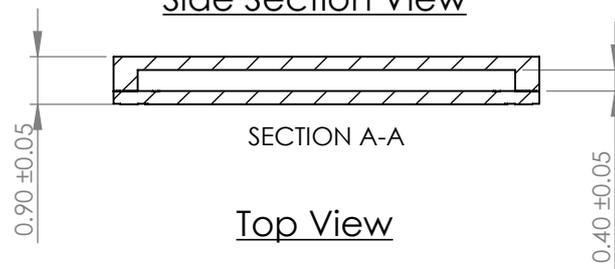
Package Dimensions:

Bottom View

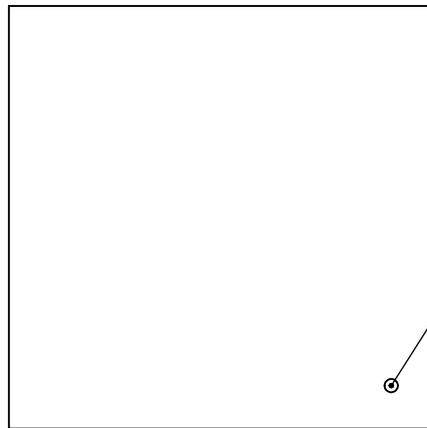
Package Dimensions
QFN 8x8(44 Pin)



Side Section View



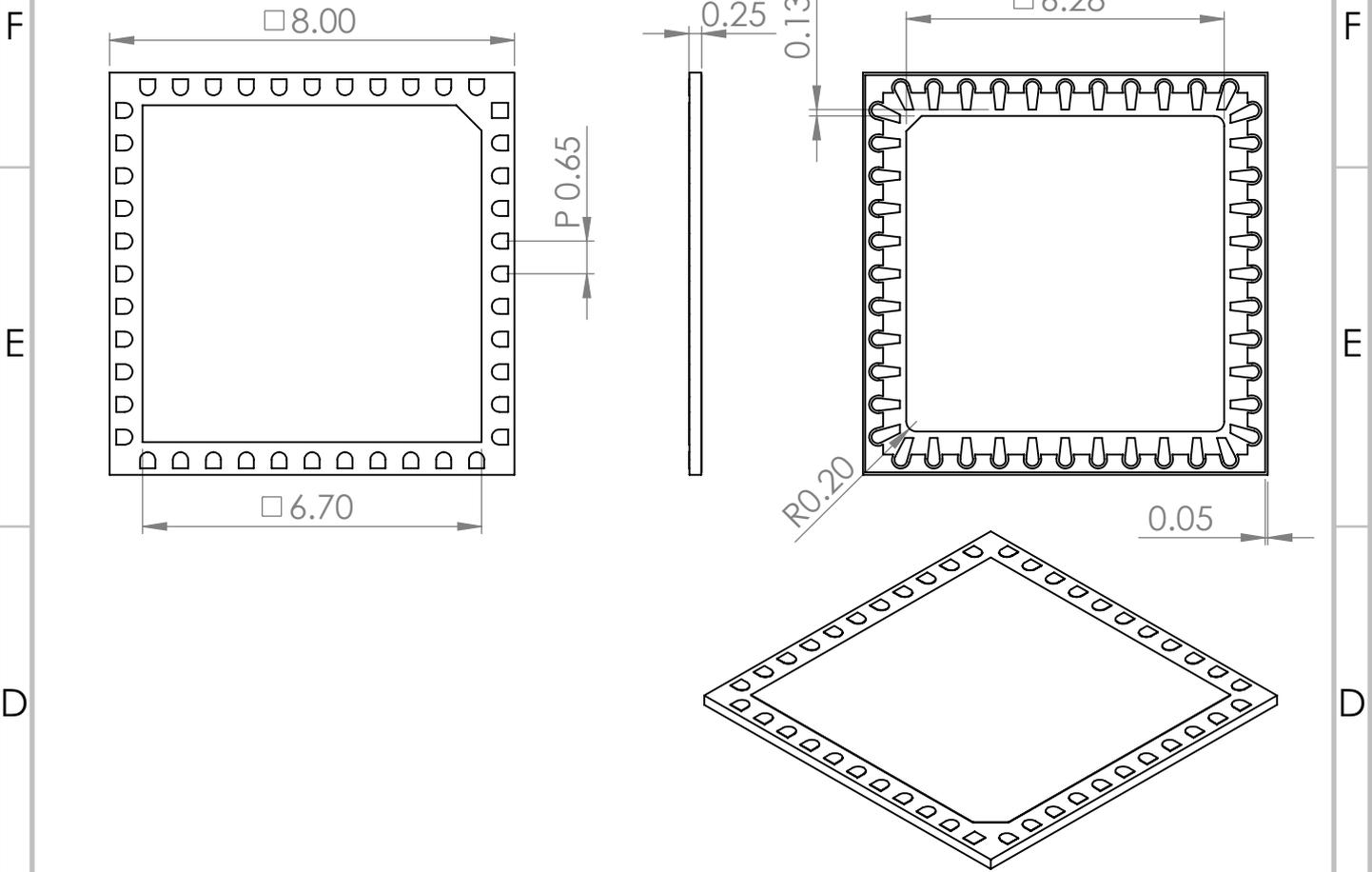
Top View



Notes:

1. Substrate material Mitubishi HL832NS(LC) S-glass
2. Lid material Rogers RO4003
3. Top substrate layout, standard iNPACK design customized per customers request
4. EM and thermal simulation based designs are available as customized solutions
5. Sealing- near hermetic adhesive
6. Marking per customers request
7. Center pad is GND
8. CuMo / Cu coin can be embedded at GND pad or fill Cu via structure
9. Conforms to JEDEC standard JESD-30 MO-220
10. All dimensions are in millimeters

Substrate 8x8 44 :



Lid 8x8 :

